

TECHNICAL DATA SHEET



Purge-Atory Purging Compound



Product Description

Purge-Atory is a revolutionary heavy-duty purging compound. Recommended for use with gas emitting resins such as Delrin® and acetal. Requires no mixing or preparation time. Formulated with a SAN resin carrier, Purge-Atory purging compound is safe to purge right through the mold, saving time, material and money. All ingredients are GRAS rated so it is safe to use for food packaging applications. For use with injection molding, extrusion and blow molding.

Applications

Unit Package Description 48 and 1,100 pound boxes

Generic Description

Purging Compound 45 & 1,000 pounds

Purging Compoud

Net Weight Fill

858799000707

UPC Code
Appearance

Resin Pellet

Odor

None

Flash Point F

>750 degrees

Flash Point C

>400 degrees

Base Type

Resin

Evaporation Rate

N/A

HMIS Rating

0, 0, 0, None

DOT Proper Shipping Name

Not regulated, Granules, NOI

Removal

N/A

Units Per Case

45 & 1,000 pounds

Case Weight (lbs)

45 / 1,000

Working Temperature F

370 to 610 degrees

Working Temperature C

187 to 321 degrees

Propellant

N/A

N/A

NFPA Aerosol Flammability Level